ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INDUSTRIES® INDUSTRIES	burn, Illinois. All rights reserved up	nder both This docum level parts,	ent is a declaration the declaration en	on of the substance acompasses all low	es within the manufacture ver level materials for wh	er listed item. Note: i hich the manufacture	f the item is an as t has engineering	ssembly with lower responsibility.	
IPC Web Site for Information on http://www.ipc.org/IPC-175x	Veb Site for Information on IPC-1752 Standard Form Type //www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat					
Supplier Information									
Company name*	pany name* Company unique ID		Unique ID Authority			Response Date*			
onsemi	mi					2023-06-08			
Contact Name	Title - Contact		Phone - Contact*			Email - Contact*			
Product-Env-Stewards	luct-Env-Stewards Product Enviro Compliance		NA			Product-Env-Stewards@onsemi.com			
thorized Representative* Title - Representative			Phone - Representative*			Email - Representative*			
Product-Env-Stewards Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Iten	n Number Mfr Item Name	Mfr Item Name		Version	Manufacturing Site	Weight*	UOM	Unit Type	
NCP811	09GMNTXG Single-Phase Volt Interface	age Regulator with SVID	2023-06-08		PH1	118.03	mg	Each	
Manufacturing Proccess Information									
Terminal Plating / Grid Array Material	ing / Grid Array Material Terminal Base Alloy .		Peak Proce	ss Body Temperat	ure Max Time at Peak	Temperature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy 3		3	260	С	30	seconds 3			
Comments									
ATTENTION: MSL 3 Rated item requires Bake and I	Dry Pack (after electrical test)								
For more information regarding material composition	please refer to page 3								

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, is of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the complicace of its products with European Union member state laws that implement the ROHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified information. However, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the iteratification in this paragraph. If the Company and the Supplier rinto a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of hat agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.48	mg	Supplier	Silicon (Si)	7440-21-3		3.48	mg
Die Attach Solder	3.37	mg	Supplier	Silver (Ag)	7440-22-4		0.0842	mg
			А	Lead (Pb)	7439-92-1	7a	3.1172	mg
			Supplier	Tin (Sn)	7440-31-5		0.1685	mg
Lead Frame	57.28	mg	Supplier	Silver (Ag)	7440-22-4		0.2291	mg
			Supplier	Tin (Sn)	7440-31-5		0.1432	mg
			Supplier	Zinc (Zn)	7440-66-6		0.126	mg
			Supplier	Chromium (Cr)	7440-47-3		0.1432	mg
			Supplier	Copper (Cu)	7440-50-8		56.6385	mg
Mold Compound-Black	49.82	mg		Epoxy Phenol Resin	proprietary data		5.2311	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		44.5889	mg
Plating	2.76	mg	Supplier	Tin (Sn)	7440-31-5		2.76	mg
Wire Bond - Au	1.32	mg	Supplier	Gold (Au)	7440-57-5		1.32	mg